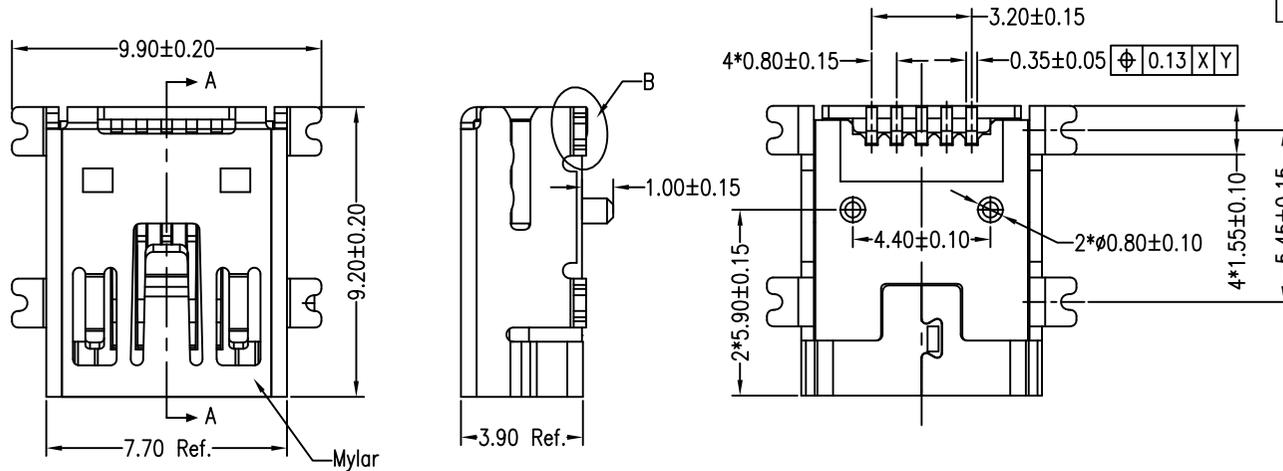


GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2021/3/28	Ken Lin
A1			Change	2022/08/18	Ken Lin
A1.1			Change Current rating: DC20.0V 2.5A Max.	2024/10/11	Ken Lin



Note:

1.Material:

1.1 Housing: LCP UL94V-0 ,Color:Black

1.2 Contact: copper alloy C5191,

AU planting Gold Flash on contact area,

AU planting 1U" Solder , 50U" Ni planting Over all.

1.3 Shell: copper alloy C2680

50U" Ni planting over all.

2.Specification:



2.1 Current rating: DC 20.0V 2.5 A Max.

2.2 Dielectric withstanding : voltage: 500 V(ac) for 1 min.

2.3 Contact resistance: 50 mΩ Max.

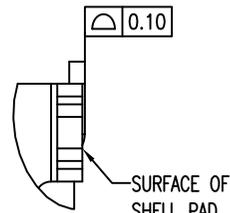
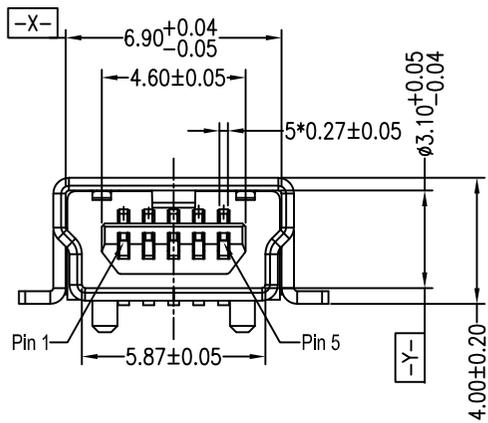
2.4 Insulation resistance: 100 MΩ Min.

2.5 Total mating force: 3.57 Kgf Max.

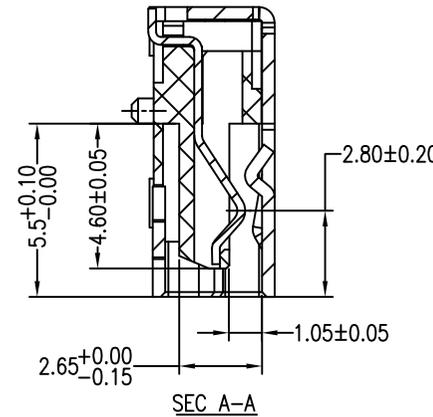
2.6 Total unmating force: 0.71 Kgf Min.



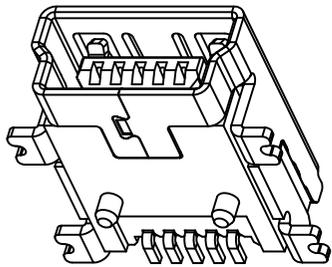
2.7 Temperature range: -40°C-85°C



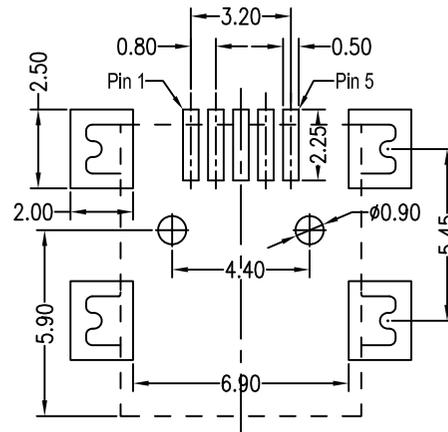
DETAIL B
SCALE 2/1



SEC A-A



3D VIEW



RECOMMENDED PCB LAYOUT

MATRIX PART NO:

MUSB 05 - 01 - 574

MATRIX USB

Pin Number

Series number

Plating
01:Gold Flash
15:15u"
30:30u"

Pin Assignment		Matrix Electronics Co.,Ltd				
Contact Number	Signal Name	TOLERANCE:	DESIGN BY :	DATE :	PART NAME:	
1	VBUS	X:X ±0.25	Ken Lin	2024/10/11	MINI USB2.0 Type-B 母座//板上式 5Pin SMT	
2	D-	X:XX ±0.15	CHECKED BY:	DATE :	PART NO.	MUSB05-01-574
3	D+	X:XXX ±0.05	Vicky Hsieh	2024/10/11	MOLD NO.	NA
4	ID	ANGLE: ±3	APPROVED BY1:	DATE :	DRAW NO.	
5	GND		Richard Hsieh	2024/10/11	SHEET NO.	1 OF 1
Shell	Shield	UNIT: mm [inch]	APPROVED BY2:	DATE :		
		SCALE:1:1 SIZE:A4	Richard Hsieh	2024/10/11		